

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A method for providing a PCB (printed circuit board) with a shield can (1;11;21;31) comprising a metal shell having with a free rim (5;15;25;35), said method comprising the steps of:

providing the PCB (12) with solder; (16);

placing the shield can (1;11;21;31) on the PCB (12) with the rim (5;15;25;35) towards the PCB; (12);

heating the PCB (12) and the shield can (1;11;21;31) to a temperature above a melting temperature of the solder; and (16);

cooling the PCB (12) and the shield can (1;11;21;31), wherein characterised in that the rim (5;15;25;35) of the shield can (1;11;21;31) is provided with an extra amount of solder (8;18) before the shield can (1;11;21;31) is placed on the PCB (12).

2. (Currently Amended) The A method according to claim 1, wherein characterised in that the rim (5;15;25;35) of the shield can (1) is provided with the extra amount of solder (8) by dipping the rim it partly into a bath of molten solder (8).

3. (Currently Amended) The A method according to claim 1, wherein characterised in that recesses (19;29) are provided at the rim (15;25) of the shield can (11;21) before the extra amount of solder (18) is applied thereto; and

wherein that the extra amount of solder (18) is applied to the recesses.

4. (Currently Amended) The A method according to claim 1 or 3, wherein characterised in that the rim (5;15;25) of the shield can (1;11;21) is provided with the extra amount of solder (8;18) by a screen-printing process.

5. (Currently Amended) The A method according to claim 1 or 2, wherein characterised

in that indentations (39) are provided at the rim of the shield can (31) before the extra amount of solder is applied thereto; and

wherein that the extra amount of solder is applied to the indentations (39).

6. (Withdrawn) A shield can (1;11;21;31) for electro-magnetically shielding an electronic component mounted on a printed circuit board (PCB) provided with solder, said shield can (1;11;21;31) comprising a metal shell with a free rim (5;15;25;35), characterised in that the rim (5;15;25;35) of the shield can (1;11;21;31) is provided with an extra amount of solder (8;18).

7. (Withdrawn) A shield can according to claim 6, characterised in that the rim (15;25) of the shield can (11;21) is provided with a plurality of recesses (19;29), each recess (19;29) being provided with an extra amount of solder (18).

8. (Withdrawn) A shield can according to claim 7, characterised in that each recess (19;29) is V-shaped.

9. (Withdrawn) A shield can according to claim 6, characterised in that the rim (35) of the shield can (31) is provided with a plurality of indentations (39), each indentation (39) being provided with an extra amount of solder.

10. (Withdrawn) A shield can according to claim 9, characterised in that each indentation (39) is V-shaped.

11. (Withdrawn) A shield can according to any one of claims 6-10, characterised in that the shield can (1;11;21;31) is box-shaped with a flat upper shell part (3;13) and four downwardly extending side pieces (4;14;24;34) with the free rim (5;15;25;35).

12. (Withdrawn) A shield can according to claim 11, characterised in that the side pieces (14;24;34) are interconnected at adjoining corners; and that each corner is provided with a leg (20) that protrudes downwards beyond the free rim (15;25;35).